L Number	Hits		DB	Time stamp
49	2958	' L	USPAT;	2003/08/01 09:14
		circuit) and (package or packaging or	US-PGPUB;	
		housing) and (lead or lead adj frame or leadframe) near2 (shape or shaped)	EPO; JPO;	
		readifame, hearz (shape of shaped)	DERWENT; IBM TDB	
50	2765	(chip or die or ic or integrated adj	USPAT;	2003/08/01 09:14
30	1 2,00	circuit) and (package or packaging or	US-PGPUB;	2003/08/01 03:14
		housing) and (lead) near2 (shape or shaped)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
51	13	'	USPAT;	2003/08/01 09:16
		circuit) and (package or packaging or	US-PGPUB;	
		housing) and (lead or leadframe or lead adj	EPO; JPO;	
		frame) near2 small adj footprint	DERWENT;	
52	875	257/696.ccls.	IBM_TDB	2003/08/01 09:18
32	0,3	2377 050.0015.	USPAT; US-PGPUB;	2003/08/01 09:18
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
53	54	257/696.ccls. and lead near3 (angled or	USPAT;	2003/08/01 09:26
		angle or inclined or incline or angling or	US-PGPUB;	
		degrees or acute or obtuse)	EPO; JPO;	
			DERWENT;	
E 4		257/602 agla and 14 / 7 3	IBM_TDB	0000/65/55
54	75	257/692.ccls. and lead near3 (angled or	USPAT;	2003/08/01 09:27
		angle or inclined or incline or angling or degrees or acute or obtuse)	US-PGPUB;	
		degrees of acute of obcuse)	EPO; JPO; DERWENT;	
		·	IBM TDB	
_	0	package and die and diepad and lead and	USPAT;	2003/07/31 15:31
		(foot or footprint) near4 (wetting or	US-PGPUB;	2003,07,31 23:31
		inclined or inclination or angled or angle	EPO; JPO;	
		or bent)	DERWENT;	
		, ,	IBM_TDB	
-	6545	(package or packaging) and (lead or foot or	USPAT;	2003/07/31 15:32
		footprint) near4 (wetting or inclined or inclination or angled or angle or bent or	US-PGPUB;	
		folded)	EPO; JPO;	
		Tordedy	DERWENT; IBM TDB	
_	6097	(package or packaging) and (lead or foot or	USPAT;	2003/07/31 15:32
		footprint) near4 (wetting or inclined or	US-PGPUB;	2003/07/31 13:32
		inclination or angled or angle or bent)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2538	(package or packaging) and (lead or foot or	USPAT;	2003/07/31 16:18
		footprint) near4 (wetting or inclined or	US-PGPUB;	
		inclination or angled or angle)	EPO; JPO;	
			DERWENT; IBM TDB	
_	554	(package or packaging) and (lead or foot or	USPAT;	2003/07/31 15:39
İ		footprint) near4 (wetting or inclined or	US-PGPUB;	-000, 0,,51 15.59
		inclination or angled or angle) and (lead or	EPO; JPO;	
		foot or footprint) near4 (beneath or under	DERWENT;	
		or underneath or below or back)	IBM_TDB	
-	326	(chip or die or ic) and (package or	USPAT;	2003/07/31 16:15
		packaging) and (lead or foot or footprint)	US-PGPUB;	
		near4 (wetting or inclined or inclination or	EPO; JPO;	
i		angled or angle) and (lead or foot or footprint) near4 (beneath or under or	DERWENT;	
		underneath or below or back)	IBM_TDB	
-	11	(package or packaging) and (lead or foot or	USPAT;	2003/07/31 16:40
		footprint) near3 solder adj wetting	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	İ		IBM_TDB	
-	914	(package or packaging or housing) and (lead	USPAT;	2003/07/31 16:40
		or lead adj frame or leadframe or package)	US-PGPUB;	
		near3 (footprint or foot adj print)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	349	(package or packaging or housing) and (lead	USPAT;	2003/07/31 16:53
		or lead adj frame or leadframe or package)	US-PGPUB;	
		near3 (footprint or foot adj print) near5	EPO; JPO;	
		(reduced or small or little or smaller or	DERWENT;	
		decrease or reduce or decreased)	IBM_TDB	
-	1572	(package or packaging or housing) and (lead	USPAT;	2003/07/31 16:53
		or lead adj frame or leadframe or package)	US-PGPUB;	
		near3 (footprint or foot adj print or area)	EPO; JPO;	
		near5 (reduced or small or little or smaller	DERWENT;	
		or decrease or reduce or decreased) not bga	IBM TDB	
-	191	(package or packaging or housing) and (lead	USPAT;	2003/08/01 09:09
		or lead adj frame or leadframe or package)	US-PGPUB;	
		near3 (footprint or foot adj print) near5	EPO; JPO;	
		(reduced or small or little or smaller or	DERWENT;	
		decrease or reduce or decreased) not bga	IBM_TDB	